# 水素添加 In<sub>2</sub>O<sub>3</sub> 薄膜の固相結晶化過程における金属-半導体遷移

## Metal-semiconductor transition of hydrogen-doped In<sub>2</sub>O<sub>3</sub> via solid-phase crystallization.

## <sup>O</sup>(D) Xiaoqian Wang<sup>1</sup>, Mamoru Furuta<sup>1</sup>

### Kochi Univ. of Tech.<sup>1</sup>

### E-mail: 258011v@gs.kochi-tech.ac.jp

Metal oxide semiconductors have attracted a lot of attention for use as an active channel layer of thin film transistors (TFTs) for next-generation flat-panel displays, nonvolatile memories, and so on, due to its outstanding electrical and optical properties.

Our group reported the metal-semiconductor transition (MST) of hydrogen-doped indium oxide (InO<sub>x</sub>:H) films via low-temperature (~200 °C) solid phase crystallization (SPC) in ambient air. Field effect mobility of over 100 cm<sup>2</sup>/Vs have been obtained from the TFTs with nondegenerate InO<sub>x</sub>:H channels [1,2]. However, the MST mechanism of the InO<sub>x</sub>:H films has not clarified yet. In this presentation, the effect of oxygen and hydrogen during the deposition on carrier density (Ne) of SPC- InO<sub>x</sub>:H films have been investigated.

The 50-nm-thick InO<sub>x</sub>:H films were deposited by RF magnetron sputtering in Ar, O<sub>2</sub>, and H<sub>2</sub> gases. The O<sub>2</sub> gas flow ratio (R[O<sub>2</sub>]) was varied from 2 to 4%, while H<sub>2</sub> gas flow ratio (R[H<sub>2</sub>]) was varied from 1 to 9%. The InO<sub>x</sub>:H films were then annealed in ambient air at 250 °C for 1 to 60 min.

Figure 1(a) shows the *in-situ* Hall measurement results of the  $InO_x$ :H films deposited at  $R[O_2]$ - $R[H_2]$  of 3-5 and 4-5%. No significant difference of Ne was observed between the films annealed in vacuum, whereas Ne of both the films decreases significantly at 190 °C owing to the SPC in air. Figure 1(b) shows the annealing time dependence of the Ne of  $InO_x$ :H films. We found that the required annealing time for MST strongly depended on both the  $R[O_2]$  and  $R[H_2]$ . The  $InO_x$ :H film deposited at  $R[O_2]$ - $R[H_2]$  of 4-5% exhibited a rapid MST within 5 min, while compared with the film deposited at 4-5%, the film deposited at 3-5% showed a slow MST around 30 min. The effect of deposition condition on Ne reduction during annealing in air will be discussed in detail.



Figure 1. (a) *In-situ* Hall measurement results of the InO<sub>x</sub>:H films measured in air and vacuum. (b) Annealing time dependence of the Ne for the InO<sub>x</sub>:H films at 250 °C.
Reference [1] Y. Magari, *et al.*, Nature communications, 13, 1078 (2022).

[2] T. Kataoka, et al., Materials, **15(1)**, 187, (2022).